

4th D/TOS-QCA Final Presentation Day, January 30th, 2001.

Radiation Evaluation of Fast 4-Mbit SRAM's for the COROT DPU.

by

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Abstract

This presentation will address radiation behaviour, both TID and SEE, of fast 4Mbit SRAM evaluated for the COROT DPU. Co-60 TID results as well as proton and heavy ion SEE results will be detailed for Samsung K6R4008C1C, Samsung K6R4008V1C and Hitachi HM6216255H.



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Objective:

To Radiation Evaluate 4 types of Fast 4-Mbit SRAMs

- Having Samsung "C" Version as the prime candidate
- Preliminary data in year 2000

ESA/ESTEC Space Science (SCI-SO)

- Thierry Beaufort/Bengt Johlander
- 1st October 2000 - Request for Radiation Evaluation
- 23rd October 2000 - Parts Ordered
- 30th October 2000 - Parts at ESTEC
- 17th November 2000 - HIF Testing at UCL, Belgium
- 13th December 2000 - PIF Testing at PSI, Switzerland
- 29th December 2000 - TID Completed at ONERA-CERT, France
- 30th January 2001 - Final Test Reports available at our www page:

<https://escies.org/public/radiation/>



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4-Mbit High-Speed SRAM Types Tested:

| Manufacturer | Type | Speed | Power | TID Report | SEE Report |
|--------------|------------|-------|-------|----------------|----------------|
| Samsung | K6R4008C1C | 12 ns | 5.0 V | ESA QCA0102T C | ESA QCA0102S C |
| Samsung | K6R4008V1C | 12 ns | 3.3 V | ESA QCA0103T C | ESA QCA0103S C |
| Samsung | KM684002AJ | 15 ns | 5.0 V | - | ESA QCA0101S C |
| Hitachi | MTW32N20E | 15 ns | 5.0 V | ESA QCA0104T C | ESA QCA0104S C |

Packages: Samsung 36-SOJ, Hitachi 44-SOJ



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4-Mbit SRAM - Radiation Evaluation:

TID Co-60 Dose rate 200 rad(Si)/hour

- Parametric Testing having
- 4 parts/type Biased during irradiation
- 1 part/type as reference

SEE Heavy ion – ^{10}B , ^{20}Ne , ^{40}Ar and ^{84}Kr ions

- Static/Dynamic Testing having
- 2 parts/type Single Event Effect Tested (SEE)
- De-capping – plastic packages

SEE Proton – Energy: 60.9, 40.6, 33.3, 23.3, 17.6, 12.4 & 7.3 MeV

- Static Testing having
- 2 parts/type Single Event Effect Tested (SEE)

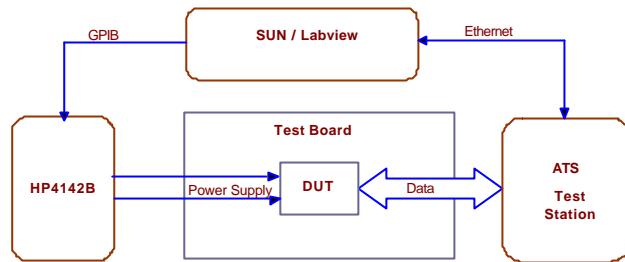


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TID Co-60: Parametric Test Set-Up



HIREX ENGINEERING - Test program principle



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TID Co-60: Electrical Parameters I.

| SYMBOL | PARAMETER | TESTS CONDITIONS | LIMIT | | UNIT |
|--------|-----------------------------------|---|-------|-----|---------------|
| | | | Min | Max | |
| ILLI | Input Leakage Current Low Level | $V_{in}(\text{under test}) = V_{IL}$ $V_{in}(\text{remaining inputs}) = V_{IH}$ output unloaded | -2 | 2 | μA |
| IHLI | Input Leakage Current High Level | $V_{in}(\text{under test}) = V_{IH}$ $V_{in}(\text{remaining inputs}) = V_{IL}$ output unloaded | -2 | 2 | μA |
| ILLO | Output Leakage Current Low Level | $V_{out}(\text{under test}) = V_{IL}$ $V_{out}(\text{remaining outputs}) = \text{tristate}$ $CS^* = OE^* = V_{IH}$ Remaining inputs V_{IL} or V_{IH} | -2 | 2 | μA |
| IHLO | Output Leakage Current High Level | $V_{out}(\text{under test}) = V_{IH}$ $V_{out}(\text{remaining outputs}) = \text{tristate}$ $CE^* = OE^* = V_{IH}$ Remaining inputs V_{IL} | -2 | 2 | μA |
| VOH | Output Voltage High Level | $I_{OH} = -4 \text{ mA}$ | 2.4 | | V |
| VOL | Output Voltage Low Level | $I_{OL} = 8 \text{ mA}$ | | 0.4 | V |



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TID Co-60: Electrical Parameters II.

| SYMBOL | PARAMETER | TESTS CONDITIONS | LIMIT | | UNIT |
|-------------------------|--|---|-------|-----|------|
| | | | Min | Max | |
| ICC | Operating Power Supply Current | CS* = V ^L OE* = V ^H F = 80 MHz outputs unloaded | | 160 | mA |
| ISB | Standby Power Supply Current | CS* = OE* = V ^H Outputs unloaded | | 10 | mA |
| t _{AA L->H} | Address Access Time | Output Load : 50 Ω | | 12 | ns |
| t _{AA H->L} | Address Access Time | Output Load : 50 Ω | | 12 | ns |
| t _{AS} | Address setup time | Output Load : 50 Ω | 0 | | ns |
| Zero | Functional Test 1: Test Pattern: All 0 | Frequency=80MHz | | | |
| One | Functional Test 1: Test Pattern: All 1 | Frequency=80MHz | | | |
| Checkerboard | Functional Test 1: Test Pattern: Checkerboard | Frequency=80MHz | | | |
| *Checkerboard | Functional Test 1: Test Pattern: Complementary Checkerboard | Frequency=80MHz | | | |

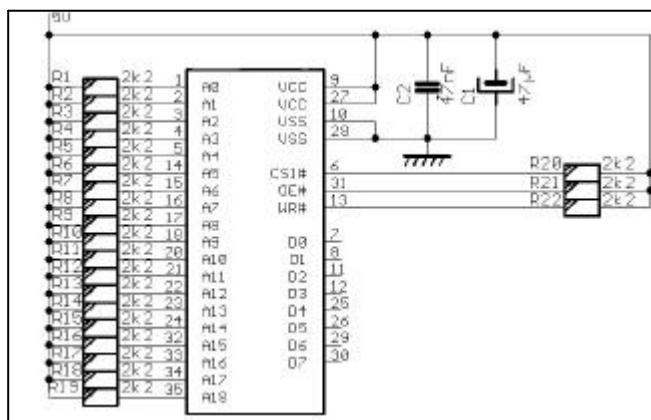


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TID Co-60: 4-Mbit SRAM Bias Conditions



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TID Co-60: Source ONERA-CERT/Irradiation Conditions

| Irr. Steps Krads(Si) | Dose Rate Krads(Si)/h | Ann. Steps Hours | Temp. °C |
|-------------------------|--------------------------|---------------------|-------------|
| 0 | | | |
| 4.6 | 0.2 | | 25 |
| 10.0 | 0.2 | | 25 |
| 14.8 | 0.2 | | 25 |
| 19.0 | 0.2 | | 25 |
| 31.8 | 0.2 | | 25 |
| 47.2 | 0.2 | 0 | 25 |
| | | 24 | 25 |
| | | 192 | 100 |



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TID Co-60: Example of Test Results-Total 108 Parameters/type

| Test Step Serial # | Initial | 5 krads | 10 krads | 14,8 krads | 19 krads | 31,8 krads | 47,2 krads |
|-----------------------|-----------|-----------|-----------|------------|-----------|------------|------------|
| 0 Ref. | 1,560E-02 | 1,560E-02 | 1,600E-02 | 1,570E-02 | 1,580E-02 | 1,570E-02 | 1,550E-02 |
| 1 | 1,650E-02 | 1,610E-02 | 1,730E-02 | 1,670E-02 | 1,760E-02 | 1,530E-01 | 2,000E-01 |
| 2 | 1,600E-02 | 1,600E-02 | 1,670E-02 | 1,620E-02 | 1,690E-02 | 1,450E-01 | 2,000E-01 |
| 3 | 1,580E-02 | 1,570E-02 | 1,640E-02 | 1,580E-02 | 1,730E-02 | 1,840E-01 | 2,000E-01 |
| 4 | 1,620E-02 | 1,610E-02 | 1,690E-02 | 1,630E-02 | 1,770E-02 | 1,820E-01 | 2,000E-01 |
| Statistics | | | | | | | |
| Min | 1,580E-02 | 1,570E-02 | 1,640E-02 | 1,580E-02 | 1,690E-02 | 1,450E-01 | 2,000E-01 |
| Max | 1,650E-02 | 1,610E-02 | 1,730E-02 | 1,670E-02 | 1,770E-02 | 1,840E-01 | 2,000E-01 |
| Mean | 1,613E-02 | 1,598E-02 | 1,682E-02 | 1,625E-02 | 1,737E-02 | 1,660E-01 | 2,000E-01 |
| Sigma | 2,986E-04 | 1,893E-04 | 3,775E-04 | 3,697E-04 | 3,594E-04 | 1,992E-02 | 9,505E-11 |

| Test Step Serial # | 24 hours | 192 hours |
|-----------------------|-----------|-----------|
| 0 Ref. | 1,600E-02 | 1,540E-02 |
| 1 | 2,000E-01 | 1,770E-02 |
| 2 | 2,000E-01 | 1,730E-02 |
| 3 | 2,000E-01 | 1,690E-02 |
| 4 | 2,000E-01 | 1,790E-02 |
| Statistics | | |
| Min | 2,000E-01 | 1,690E-02 |
| Max | 2,000E-01 | 1,790E-02 |
| Mean | 2,000E-01 | 1,745E-02 |
| Sigma | 9,505E-11 | 4,435E-04 |

Parameter : Operating Power Supply Current: ICC

Iout=0A ; 15ns Cycle Time ; ; Vin = Vil/Vih

Unit= A,

Spec limit max: 16,0E-2



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TID Co-60: Test Results for Hitachi HM6216255H - ISB

ISB_CMOS

X 0 Ref.
□ 1
▽ 2
△ 3
▼ 4

Unit: A

Irradiation steps (krads)

Parameter : Standby Power Supply Current: ISB_CMOS

15ns Cycle Time ; Vin = Vil/Vih

Spec limit max: 50,0E-3 A

Spec limits are represented in bold (blue) line on the graph.



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TID Co-60: Summary Results - Krad(Si)

| Manufacturer | Type | Speed | Power | Failing Parameters | Krad(Si) Level |
|--------------|------------|-------|-------|--------------------|----------------|
| Samsung | K6R4008C1C | 12 ns | 5.0 V | None | 47.2 |
| Samsung | K6R4008V1C | 12 ns | 3.3 V | None | 47.2 |
| Hitachi | MTW32N20E | 15 ns | 5.0 V | Functionality # | 19.0 |

Fully recovered after annealing (also parametric)



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SEE Heavy Ion: HIREX Generic In-house Test Equipment

Test Set-up

- Modular rack/Generic memory test board

Test Configurations

1) Dynamic

- Write the entire memory
- Memory continuously irradiated
- Read/Write sequentially by pages of 128 words

2) Static

- Write the entire memory
- Memory irradiated
- Read the memory outside the beam



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SEE Heavy Ion/Proton: HIF & OPTIS

UCL CYCLONE – Heavy-ion Irradiation Facility (HIF)

- $^{84}\text{Kr}^{17+}$ at 316 MeV - LET(Si) = 34.0 – 68.0 MeV/(mg/cm²)
- $^{40}\text{Ar}^{8+}$ at 150 MeV - LET(Si) = 14.1 – 28.2 MeV/(mg/cm²)
- $^{20}\text{Ne}^{4+}$ at 78 MeV - LET(Si) = 5.85 – 11.7 MeV/(mg/cm²)
- $^{10}\text{B}^{2+}$ at 41 MeV - LET(Si) = 1.7 – 3.4 MeV/(mg/cm²)

PSI OPTIS – Part of the Proton Irradiation Facility (PIF)

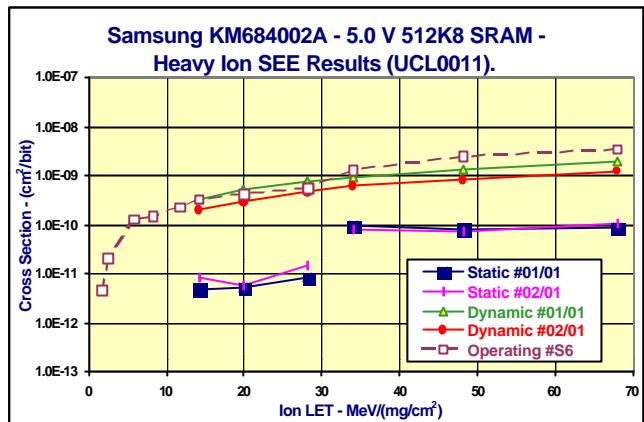
- Energy 60.9 MeV - LET(Si) = 8.50E-03 MeV/(mg/cm²)
- Energy 40.6 MeV - LET(Si) = 1.17E-02 MeV/(mg/cm²)
- Energy 33.3 MeV - LET(Si) = 1.36E-02 MeV/(mg/cm²)
- Energy 23.3 MeV - LET(Si) = 1.80E-02 MeV/(mg/cm²)
- Energy 17.6 MeV - LET(Si) = 2.25E-02 MeV/(mg/cm²)
- Energy 12.4 MeV - LET(Si) = 2.95E-02 MeV/(mg/cm²)
- Energy 07.3 MeV - LET(Si) = 4.43E-02 MeV/(mg/cm²)



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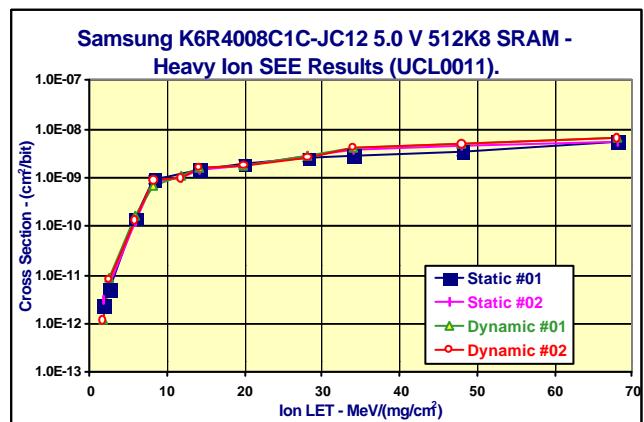
SEE Heavy Ion: KM684002A - Reference



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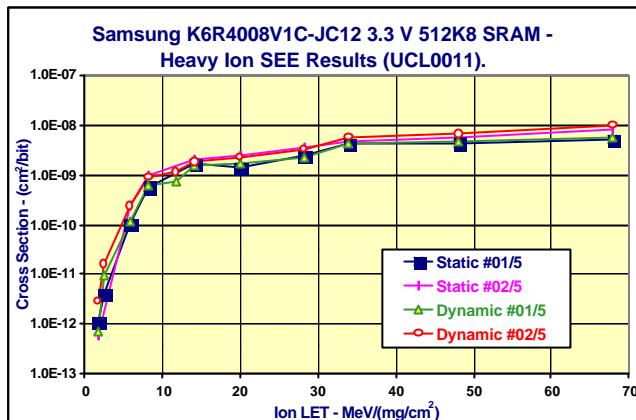
SEE Heavy Ion: K6R4008C1C - 5.0V



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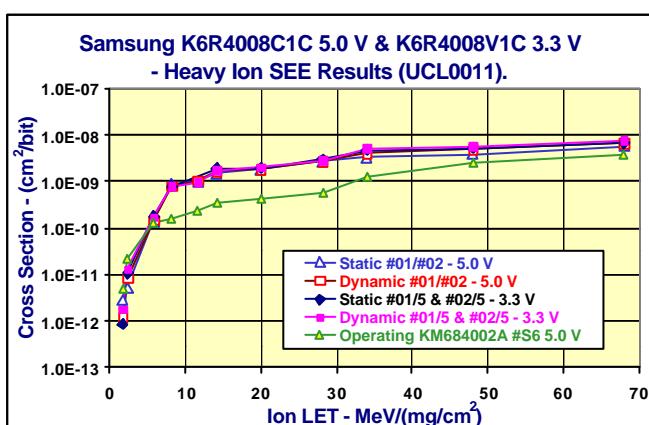
SEE Heavy Ion: K6R4008V1C - 3.3V



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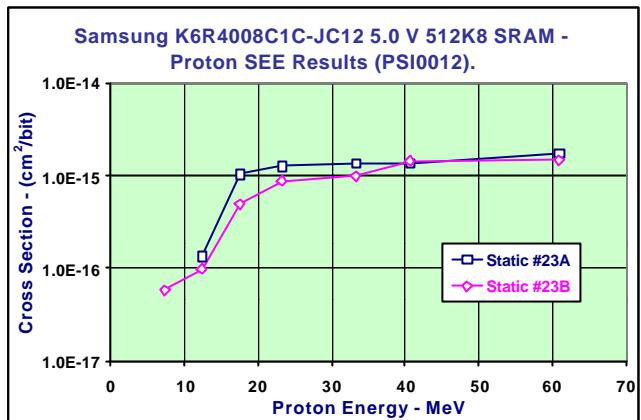
SEE Heavy Ion: K6R4008C1C - 5.0V & K6R4008V1C - 3.3V



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Ref.: D/TOS-QCA/SRAM

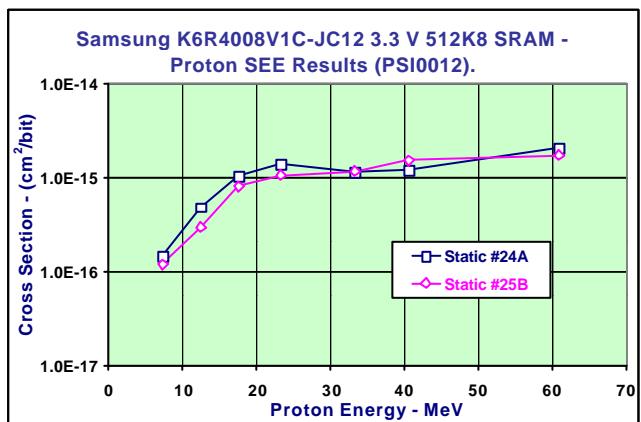
SEE Proton: K6R4008C1C - 5.0V



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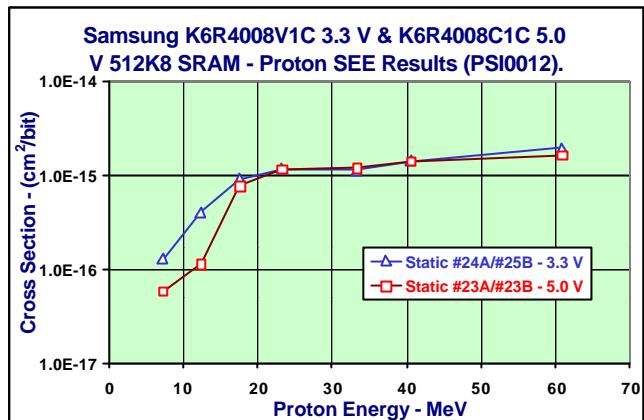
SEE Proton: K6R4008V1C - 3.3V



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Ref.: D/TOS-QCA/SRAM

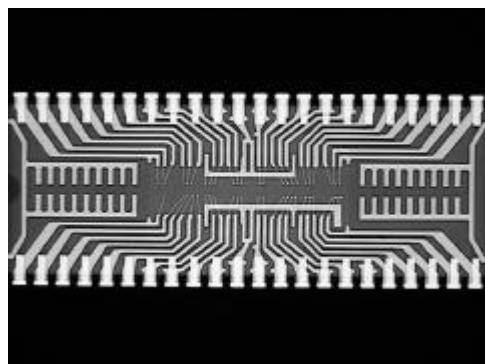
SEE Proton: K6R4008V1C - 3.3V & K6R4008C1C - 5.0V



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SEE Heavy Ion and Proton: Hitachi HM6216255H 5.0 V



SEE Heavy ion: Test not possible - see X-ray

SEE Proton: at 60 MeV – Cross section = 3.7E-18 cm²/per bit



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Ref.: D/TOS-QCA/SRAM

Radiation Summary: 4M-bit SRAM Evaluation

| Radiation Test | K6R4008C1C 5.0 V | K6R4008C1C 3.3 V | HM6216255 5.0 V | Unit |
|------------------|---------------------|---------------------|--------------------|---------------------------|
| Protr. SEU Sat.* | ~2E-15 | ~2E-15 | ~3.7E-18 | cm ² /per bit |
| Protr. SEU Th.* | 7 | 7 | 60 | MeV |
| H-ion SEU Sat.* | ~6E-9 | ~6E-9 | N.T. | cm ² /per bit |
| H-ion SEU Th.* | ~2 | ~2 | N.T. | MeV/(mg/cm ²) |
| TID | >47 | >47 | >19 | Krad(Si) |

* No SEL, row, column, block or word events were observed in any of these tests.



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